

Title (en)

METAL PASTE, BONDING METHOD AND METHOD FOR PRODUCING BONDED BODY

Title (de)

KUPFERPASTE, VERBINDUNGSVERFAHREN UND VERFAHREN ZUR HERSTELLUNG EINES GEBUNDENEN KÖRPERS

Title (fr)

PÂTE MÉTALLIQUE, PROCÉDÉ DE LIAISON ET PROCÉDÉ DE PRODUCTION D'UN CORPS LIÉ

Publication

EP 3943215 A4 20221214 (EN)

Application

EP 20778568 A 20200319

Priority

- JP 2019055538 A 20190322
- JP 2020012389 W 20200319

Abstract (en)

[origin: EP3943215A1] A metal paste for low temperature bonding at temperatures 600°C or lower, the metal paste comprising: a metal particle with an average particle size of 1 to 100 µm; a metal nanoparticle with an average particle size of 1 to 500 nm; a stress relieving material; and a dispersion medium to disperse the metal particle, metal nanoparticle, and the stress relieving material.

IPC 8 full level

B22F 1/00 (2022.01); **B22F 1/07** (2022.01); **B22F 1/107** (2022.01); **B22F 1/16** (2022.01); **B22F 7/04** (2006.01); **B22F 7/06** (2006.01); **B22F 7/08** (2006.01); **C22C 1/10** (2006.01); **C22C 5/02** (2006.01); **C22C 5/06** (2006.01); **C22C 9/00** (2006.01)

CPC (source: EP US)

B22F 1/00 (2013.01 - EP US); **B22F 1/07** (2022.01 - EP US); **B22F 1/09** (2022.01 - EP US); **B22F 1/107** (2022.01 - EP US); **B22F 1/16** (2022.01 - EP US); **B22F 7/04** (2013.01 - EP); **B22F 7/064** (2013.01 - EP US); **C22C 1/10** (2013.01 - EP); **C22C 5/02** (2013.01 - EP); **C22C 5/06** (2013.01 - EP); **C22C 9/00** (2013.01 - EP); **B22F 2007/047** (2013.01 - EP); **B22F 2301/10** (2013.01 - US); **B22F 2301/255** (2013.01 - US); **B22F 2304/054** (2013.01 - US); **B22F 2304/056** (2013.01 - US); **B22F 2304/058** (2013.01 - US); **B22F 2998/10** (2013.01 - EP); **B22F 2999/00** (2013.01 - EP)

Citation (search report)

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- [XY] US 2014287158 A1 20140925 - HEYEN JANET [US], et al
- [XY] JP 2006196245 A 20060727 - SUMITOMO ELECTRIC INDUSTRIES
- [Y] CN 107025950 A 20170808 - LI WENXI, et al
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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 3943215 A1 20220126; **EP 3943215 A4 20221214**; CN 113613811 A 20211105; JP WO2020196299 A1 20201001; TW 202100266 A 20210101; US 2022143692 A1 20220512; WO 2020196299 A1 20201001

DOCDB simple family (application)

EP 20778568 A 20200319; CN 202080023192 A 20200319; JP 2020012389 W 20200319; JP 2021509327 A 20200319; TW 109109288 A 20200319; US 202017438676 A 20200319